

DESCRIPTION

The MXD60P02 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as -2.5V. This device is suitable for use as a Battery protection or in other Switching application.

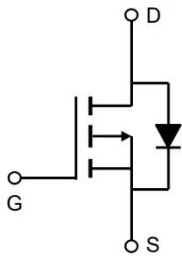
GENERAL FEATURES

- $V_{DS} = -20V$, $I_D = -60A$
 $R_{DS(ON)}(Typ.) = 11m\Omega$ @ $V_{GS} = -2.5V$
 $R_{DS(ON)}(Typ.) = 8m\Omega$ @ $V_{GS} = -4.5V$

APPLICATION

- Battery protection
- Load switch
- Uninterruptible power supply

PINOUT



Schematic diagram



Marking and pin Assignment



TO-252-3L top view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXD60P02	-55°C to 150°C	TO-252-3L	2500

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous ($V_{GS} = -4.5V$, $T_C = 25^\circ C$) ^(Note1)	I_D	-60	A
Drain Current-Continuous ($V_{GS} = -4.5V$, $T_C = 70^\circ C$) ^(Note1)	I_D	-48	A
Pulsed Drain Current ^(Note2)	I_{DM}	-200	A
Total Power Dissipation ($T_C = 25^\circ C$) ^(Note3)	P_D	60	W
Total Power Dissipation ($T_C = 70^\circ C$) ^(Note3)	P_D	48	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ C$
Thermal Resistance, Junction-to-Ambient ^(Note1)	$R_{\theta JA}$	75	$^\circ C/W$
Thermal Resistance, Junction-to-Ambient ($t \leq 10s$) ^(Note1)	$R_{\theta JA}$	40	$^\circ C/W$
Thermal Resistance, Junction-to-Case ^(Note1)	$R_{\theta JC}$	3.6	$^\circ C/W$

Note1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

Note2. The data tested by pulsed, Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

Note3. The power dissipation is limited by 175°C junction temperature



ELECTRICAL CHARACTERISTICS($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
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Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20	-22	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 100	nA

On Characteristics

Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.65	-1.0	V
Drain-Source On-State Resistance ^(Note2)	$R_{DS(ON)}$	$V_{GS}=-2.5V, I_D=-5.0A$	-	11	16	m Ω
		$V_{GS}=-4.5V, I_D=-10A$	-	8	12	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=-10V, I_D=-10A$	12	-	-	S

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, F=1.0MHz$	-	1600	-	pF
Output Capacitance	C_{oss}		-	350	-	pF
Reverse Transfer Capacitance	C_{rss}		-	300	-	pF

Switching Characteristics

Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-10V, I_D=-1A, V_{GS}=-4.5V, R_G=6.0\Omega$	-	10	-	nS
Turn-on Rise Time	t_r		-	15	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	110	-	nS
Turn-Off Fall Time	t_f		-	70	-	nS
Total Gate Charge	Q_g	$V_{DS}=-10V, I_D=-10A, V_{GS}=-4.5V$	-	63	-	nC
Gate-Source Charge	Q_{gs}		-	9.1	-	nC
Gate-Drain Charge	Q_{gd}		-	13	-	nC

Drain-Source Diode Characteristics

Continuous Source Current ^(Note1、3)	I_S	$V_G=V_D=0V$, Force Current	-	-	-50	A
Diode Forward Voltage ^(Note2)	V_{SD}	$V_{GS}=0V, I_S=-15A$	-	-	-1.2	V

Note1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

Note2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

Note3. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1. Power Dissipation

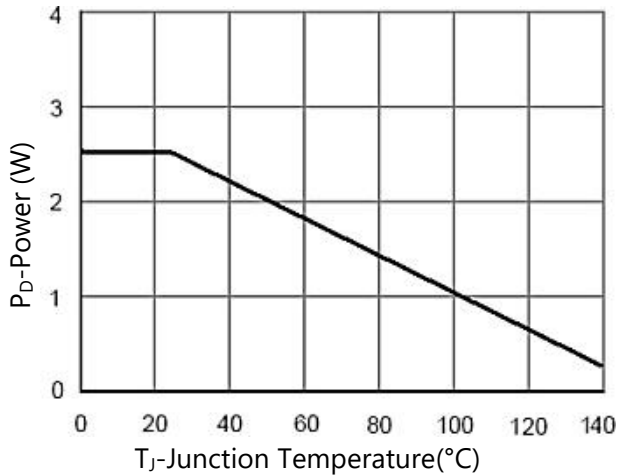


Figure 2. Drain Current

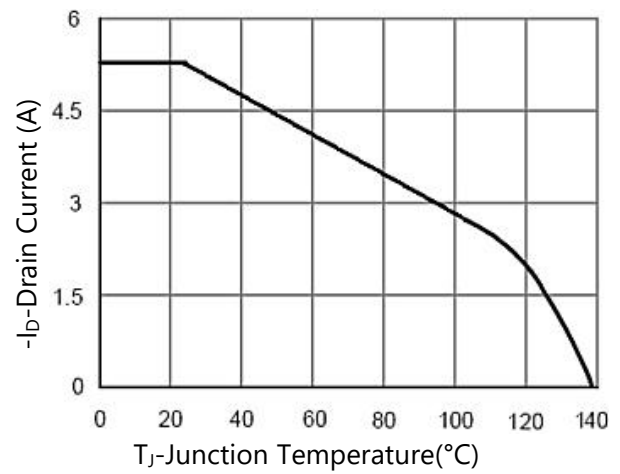


Figure 3. Output Characteristics

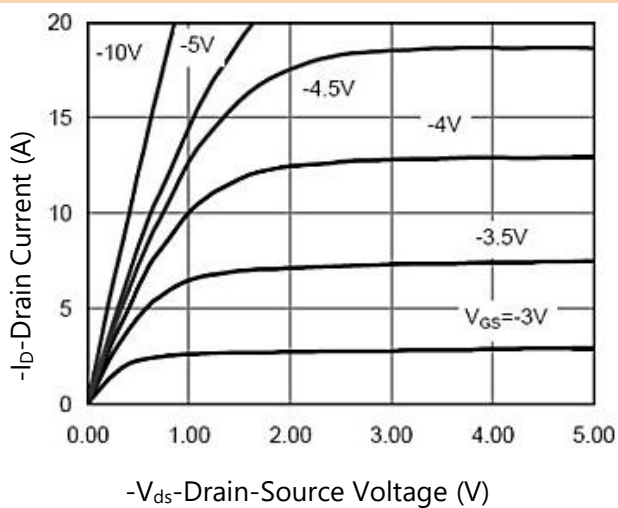


Figure 4. Drain-Source On-Resistance

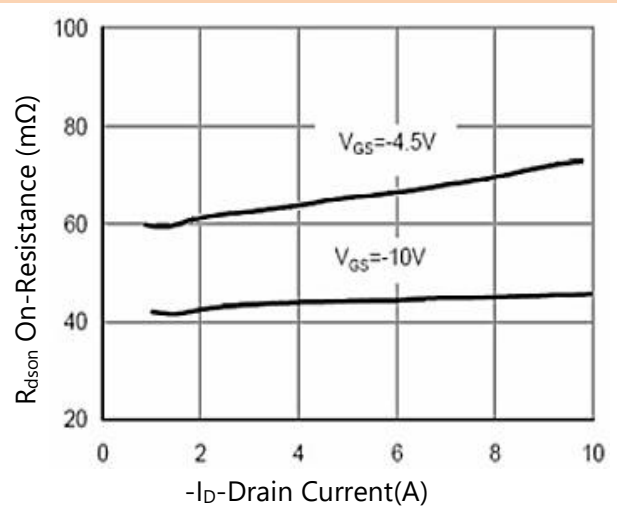


Figure 5. Transfer Characteristics

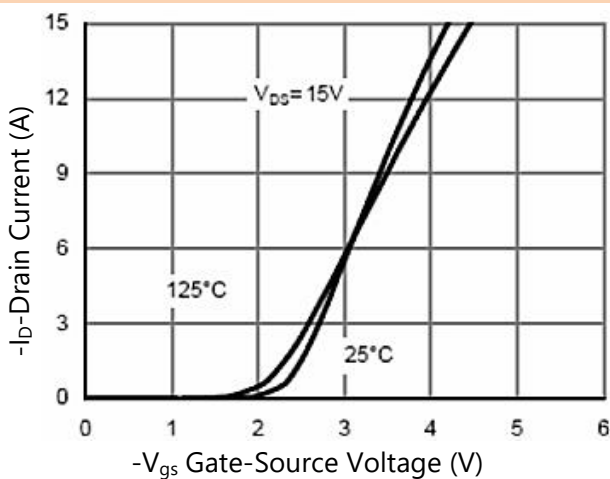
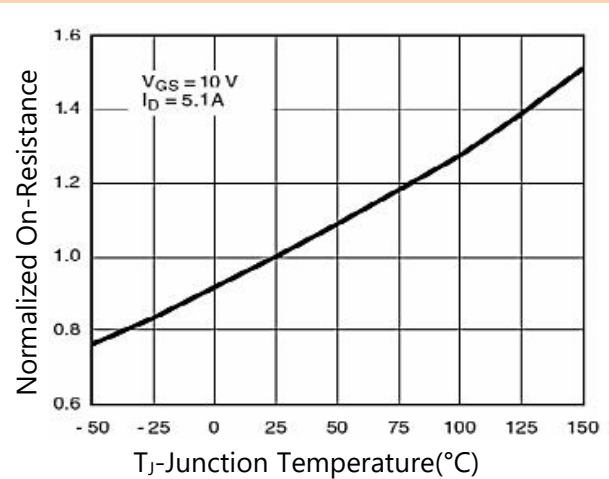


Figure 6. R_{DS(on)} vs Junction Temperature





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 7. $R_{ds(on)}$ vs V_{gs}

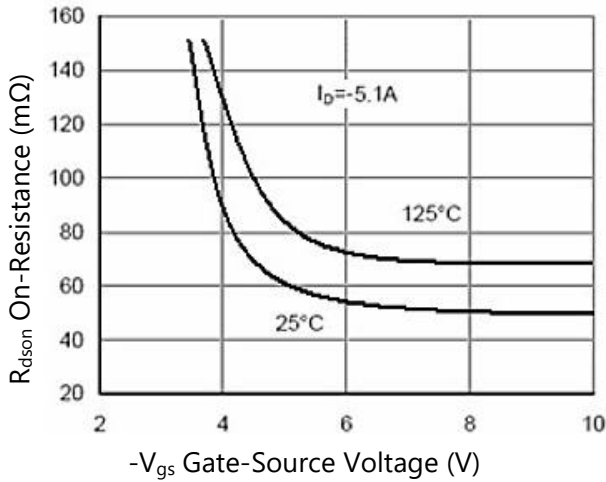


Figure 8. Capacitance vs V_{ds}

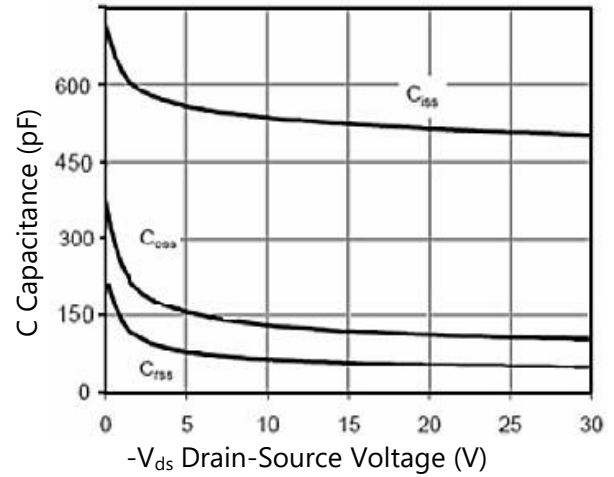


Figure 9. Gate Charge

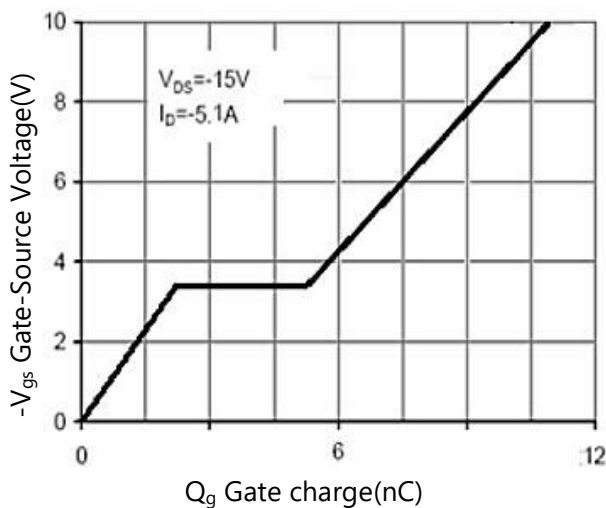


Figure 10. Source-Drain Diode Forward

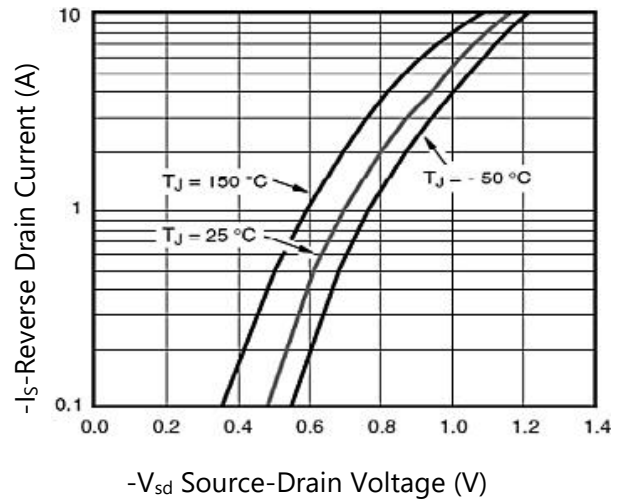
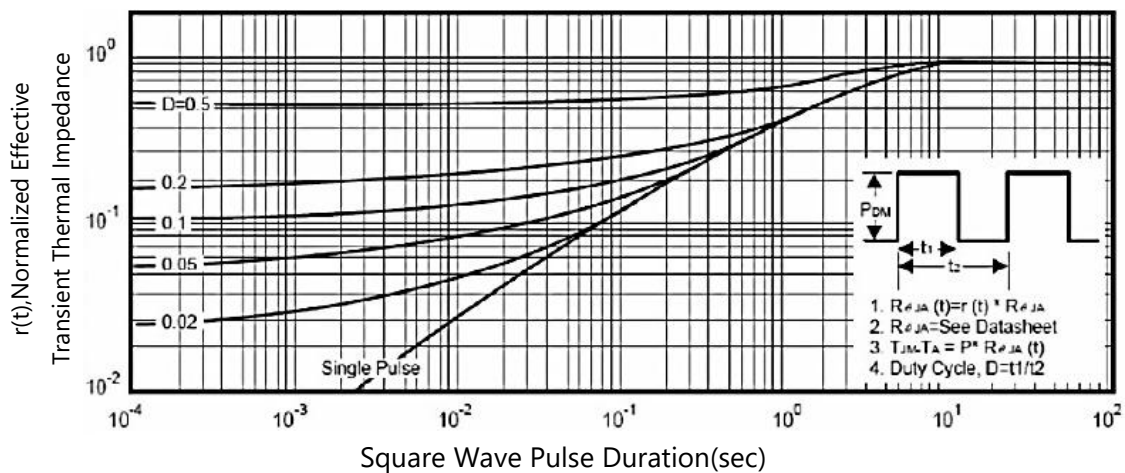


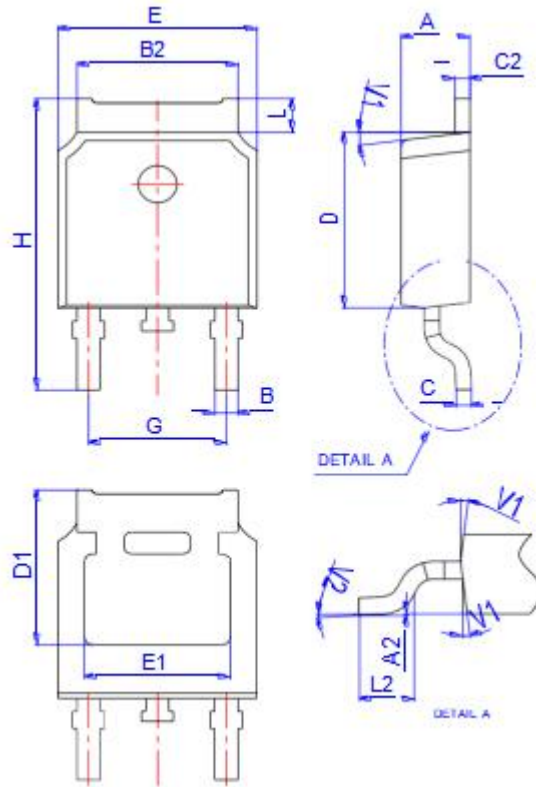
Figure 11. Normalized Maximum Transient Thermal Impedance





PACKAGE INFORMATION

TO-252-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.10	2.50	0.083	0.098
A2	0	0.10	0	0.004
B	0.66	0.86	0.026	0.034
B2	5.18	5.48	0.202	0.216
C	0.40	0.60	0.016	0.024
C2	0.44	0.58	0.017	0.023
D	5.90	6.30	0.232	0.248
D1	5.30REF		0.209REF	
E	6.40	6.80	0.252	0.268
E1	4.63	-	0.182	-
G	4.47	4.67	0.176	0.184
H	9.50	10.70	0.374	0.421
L	1.09	1.21	0.043	0.048
L2	1.35	1.65	0.053	0.065
V1	7°TYP		7°TYP	
V2	0°	6°	0°	6°